

C0603X132F4HACTU

Aliases (C0603X132F4HAC7867)

Specifications

SMD Comm X8R HT150C Flex, Ceramic, 1,300 pF, 1%, 16 VDC, X8R, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



General Information	
Series	SMD Comm X8R HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	7.3 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

W	0.8mm +/-0.15mm	To
Т	0.8mm +/-0.15mm	V
S	0.4mm MIN	D
В	0.45mm +/-0.15mm	To
		To
Packaging Specifications		

Capacitance	1,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	16 VDC
Dielectric Withstanding Voltage	40 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

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